

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
BUDONG YOU	08/11/2015
ZHENG LYU	08/11/2015
XIANGUO HUANG	08/11/2015
CHUAN PENG	08/11/2015
RECEIVING PARTY DATA	
Name:	SILERGY SEMICONDUCTOR TECHNOLOGY (HANGZHOU) LTD.
Street Address:	A1501, TECHNOLOGY MANSION, EASTERN SOFTWARE PARK, NO. 90, WENSAN ROAD, ZHEJIANG PROVINCE
City:	HANGZHOU
State/Country:	CHINA
Postal Code:	310012
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14823224
CORRESPONDENCE DATA	
Fax Number:	(612)334-3312
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	612-334-3222
Email:	ewolfe@wck.com
Correspondent Name:	JUDSON K. CHAMPLIN
Address Line 1:	900 SECOND AVENUE SOUTH
Address Line 2:	SUITE 1400
Address Line 4:	MINNEAPOLIS, MINNESOTA 55402
ATTORNEY DOCKET NUMBER:	S279.0026US1
NAME OF SUBMITTER:	JUDSON K. CHAMPLIN
SIGNATURE:	/Judson K. Champlin/
DATE SIGNED:	08/11/2015
Total Attachments: 2	
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ASSIGNMENT

Attorney Docket No.

S279.0026US1

WHEREAS, we, Budong YOU of Hangzhou, Zhejiang Province, CHINA; Zheng LYU of Hangzhou, Zhejiang Province, CHINA; Xianguo HUANG of Hangzhou, Zhejiang Province, CHINA; and Chuan PENG of Hangzhou, Zhejiang Province, CHINA (hereinafter referred to as ASSIGNORS), are the inventors of an invention described in an application for Letters Patent entitled METHOD FOR MANUFACTURING CMOS STRUCTURE, the application having been executed on even date herewith, and/or being identifiable in the United States Patent and Trademark Office by Application No. 14/823,224, filed 2015-08-11; and

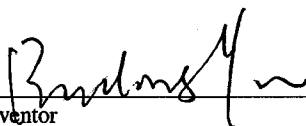
WHEREAS, Silergy Semiconductor Technology (Hangzhou) Ltd. (hereinafter referred to as ASSIGNEE), a corporation organized and existing under the laws of the State of CHINA, and having offices at A1501, Technology Mansion, Eastern Software Park, No. 90, Wensan Road, Hangzhou, Zhejiang Province, CHINA 310012, is desirous of acquiring the entire right, title and interest in and to the invention, the application and any and all Letters Patent(s) or similar legal protection, foreign or domestic, to be obtained therefor;

NOW, THEREFORE, for good and valuable consideration, the receipt and adequacy of which is hereby acknowledged, we transfer to Assignee, its successors and assigns, our entire right, title and interest in and to the invention, the above-identified application(s), corresponding domestic and foreign applications claiming rights or benefits to the above-identified application(s) including non-provisional applications, continuation applications, continuing applications, divisional applications, reissue applications, reexamination applications, design applications and continuation-in-part applications, all Letters Patent(s) or similar legal protection issuing thereon, and all rights and benefits under any applicable treaty or convention, including all rights of priority; and we authorize the Director of the United States Patent and Trademark Office or foreign equivalent thereof to issue the Letters Patent or similar legal protection to the Assignee.

We authorize the Assignee, its successors and assigns, to insert in this instrument the filing date and serial number of the application when ascertained.

We authorize the Assignee, its successors and assigns, or anyone it may properly designate, to apply for Letters Patent or similar legal protection, in its own name if desired, in any and all foreign countries.

We represent to the Assignee, its successors and assigns, that we have not and shall not execute any writing or do any act whatsoever conflicting with this Assignment. We, our executors or administrators, will at any time upon request, without additional consideration, but at the expense of the Assignee, its successors and assigns, execute such additional writings and do such additional acts as the Assignee, its successors and assigns, may deem desirable to perfect its enjoyment of this grant, and render all assistance in making application for and obtaining, maintaining, and enforcing the Letters Patent or similar legal protection on the invention in any and all countries.



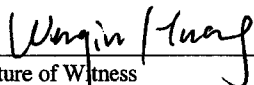
Signature of Inventor

Date : 2015.08.11

Budong YOU

Printed Name of Inventor

Residence of Inventor:
A1501, Technology Mansion, Eastern Software Park,
No. 90, Wensan Road, Hangzhou, Zhejiang Province
310012 CHINA



Signature of Witness

Date : 2015.08.11

Printed Name of Witness

Residence of Witness:
A1501, Technology Mansion, Eastern
Software Park, No. 90, Wensan Road, Hangzhou
Zhejiang Province 310012 CHINA

ASSIGNMENT

Attorney Docket No.

S279.0026US1

Zheng Lyu
Signature of Inventor

Date : 2015.08.11

Zheng LYU
Printed Name of Inventor

Residence of Inventor:

A1501, Technology Mansion, Eastern Software Park,

No. 90, Wensan Road, Hangzhou, Zhejiang Province

310012 CHINA

Xianguo HUANG
Signature of Inventor

Date : 2015.08.11

Xianguo HUANG
Printed Name of Inventor

Residence of Inventor:

A1501, Technology Mansion, Eastern Software Park,

No. 90, Wensan Road, Hangzhou, Zhejiang Province

310012 CHINA

Chuan Peng
Signature of Inventor

Date : 2015.08.11

Chuan PENG
Printed Name of Inventor

Residence of Inventor:

A1501, Technology Mansion, Eastern Software Park,

No. 90, Wensan Road, Hangzhou, Zhejiang Province

310012 CHINA

Wangjin Huang
Signature of Witness

Date : 2015.08.11

Printed Name of Witness

Residence of Witness:

A1501, Technology Mansion, Eastern
Software Park No.90, Wensan Road.

Hangzhou, Zhejiang Province 310012 CHINA.

Wangjin Huang
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Date : 2015.08.11

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A1501, Technology Mansion Eastern Park
No.90, Wensan Road, Hangzhou, Zhejiang

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